

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
De Yuan Xiao	10/31/2008
Guo Qing Chen	10/26/2001
RECEIVING PARTY DATA	
Name:	Semiconductor Manufacturing International (Shanghai) Corporation
Street Address:	18 Zhang Jiang Road
Internal Address:	Pudong New Area
City:	Shanghai
State/Country:	CHINA
Postal Code:	201203
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12258956
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ATTORNEY DOCKET NUMBER:	021653-024600US
NAME OF SUBMITTER:	Dah-Bin Kao

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Total Attachments: 7
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**PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

DE YUAN XIAO et al.

Application No.: 12/258,956

Filed: October 27, 2008

For: METHOD AND SYSTEM FOR
FORMING CONDUCTIVE BUMPING
WITH COPPER INTERCONNECTION

Customer No.: 20350

Confirmation No.: 1027

Examiner: Chris C Chu

Art Unit: 2815

**COMMUNICATION
REGARDING ASSIGNMENT
OF PATENT APPLICATION**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Commissioner:

Submitted for recordation is executed assignment of this Application by one of the two inventors: De Yuan Xiao.

The second inventor, Mr. Guo Qing Chen, no longer works at Semiconductor Manufacturing International (Shanghai) Corporation (SMIC) and cannot be reached for signing the declaration and assignment of this Application. A petition under 37 C.F.R. §147(a) for non-signing inventor was filed on behalf of Mr. Guo Qing Chen. The petition was granted July 13, 2009. In addition, Mr. Guo Qing Chen has conveyed the right of all his company-related inventions to Semiconductor Manufacturing International (Shanghai) Corporation (SMIC) in an EMPLOYEE INTELLECTUAL PROPERTY RIGHT AGREEMENT. A Chinese version of the agreement signed by Mr. Mr. Guo Qing Chen is hereby submitted for recordation. Also submitted is an English version of the agreement provided by SMIC.

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Application No.: 12/258,956
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PATENT

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at (650) 326-2400.

Respectfully submitted,

/Dah-Bin Kao/

Dah-Bin Kao
Reg. No. 53,092

KILPATRICK TOWNSEND & STOCKTON LLP
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PATENT
REEL: 026025 FRAME: 0398

Semiconductor Manufacturing International Corporation
中芯国际集成电路制造(上海)有限公司

智能财产所属权同意书

我 Gary Chen 作为中芯国际集成电路制造(上海)有限公司(SMIC)的一名工作人员, 我所有之一切和公司业务有关的发明创造都属于公司所有, 我自己完全没有所属权。发明创造方面包括:

- 半导体装置、设备、器件或方法方面, 设计或发展。
- 制程或是设备上之发明或发展。
- 制造方法方面之改良。
- 在半导体工业或科学领域, 任何形式的智力开发中之理论或实践上的发明发展。

我同意 SMIC 有完全之所属权, 可以由 SMIC 使用安排和处理。即使我离开 SMIC 2 (至少两年) 年之内, 相关(上述之项目)之创造仍然属于 SMIC 所有。(SMIC 将按您发明成果贡献大小给予奖励)

SMIC 要求员工决不侵犯别家公司之智能财产权, 或同意未经合法手续, 决不非法挪用别人智能财产(包括资料, 文件或任何与 IP 有关的财产)。

我同意不侵占他人的知识产权, 未经履行合法手续不得非法使用他人的知识产权(包括资料、文件或任何与 IP 有关的智力成果)。我决不能抄袭、仿效、侵害、复制第三人的专利权、商标专用权、著作权或任何违反法律的行为。

签名: U. Chen 日期: 10/26/2001

**本同意书须于寄回聘书日、报到日、试用期满日各签认一次。

Semiconductor Manufacturing Int'l (Shanghai) Corporation

INTELLECTUAL PROPERTY RIGHT AGREEMENT

I, _____, as an employee of Semiconductor Manufacturing Int'l (Shanghai) Corporation (SMIC), agree that: any invention-creation which is made by me and is related to business of the company belongs to the company. I have no right in said invention-creation at all. Said invention-creation includes:

- ① design or improvement on semiconductor device, equipment, element, or method;
- ② design or improvement on manufacture procedure or equipment;
- ③ improvement on manufacture method;
- ④ any form of intellectual or practical invention-creation in the semiconductor industry or scientific field development.

I agree that SMIC has complete right in said invention-creation, and SMIC can use and dispose it. Even any related invention-creation as described above that is made within two (at least two years) years since the termination of my employment from SMIC still belongs to SMIC. (SMIC will reward the inventor according to the contribution of the invention achievement.)

SMIC requires that an employee should not infringe other company's intellectual property, or illegally use other's intellectual property (including information, document, or any intellectual achievement related to IP) without authorization.

I agree that I'll not infringe other's intellectual property, or illegally use other's intellectual property (including information, document, or any intellectual achievement related to IP) without authorization. I'll not plagiarism, imitate, infringe, copy a third party's patent right, exclusive right of trademark, or copy right, or carry out any actions against law.

Signature _____ Date _____



UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents
United States Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450
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JUL 13 2009

In re Application of
Xiao and Chen
Application No.: 12/258,956
Filed: October 27, 2008
Attorney Docket No: **021653-024600US**
For: METHOD AND SYSTEM FOR FORMING CONDUCTIVE BUMPING
WITH COPPER INTERCONNECTION

: **OFFICE OF PETITIONS**
:
: DECISION ACCORDING
: RULE 47(a) STATUS
:

This is in response to the petition under 37 CFR 1.47(a), filed June 17, 2009.

The petition is **GRANTED**.

The above-identified application and papers have been reviewed and found in compliance with 37 CFR 1.47(a). This application is hereby accorded Rule 1.47(a) status.

The above-cited application was filed on October 27, 2008, without a properly executed oath or declaration. Accordingly, a "Notice to File Missing parts of Nonprovisional Application" (the "Notice") was mailed on November 17, 2008, requiring an executed oath or declaration and a surcharge for the late filing of the oath or declaration among other items. The instant petition was filed on June 17, 2009, with a request for an extension of time within the fifth month.

Petitioner has shown that inventor Chen cannot be located to execute the declaration and join the above-identified application. The above-identified application and papers have been reviewed and found in compliance with 37 CFR 1.47(a). This application is hereby accorded Rule 1.47(a) status.

As provided in Rule 1.47(c), this Office will forward notice of this application's filing to the non-signing inventors at the addresses given in the petition. Notice of the filing of this application will also be published in the Official Gazette.

This application will be directed to the Office of Patent Application Processing for further processing.

Telephone inquiries concerning this decision should be directed to the undersigned at (571) 272-3222.

Kenya A. McLaughlin
Kenya A. McLaughlin
Petitions Attorney
Office of Petitions



UNITED STATES PATENT AND TRADEMARK OFFICE

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United States Patent and Trademark Office
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JUL 13 2009

In re Application of
Xiao and Chen
Application No.: 12/258,956
Filed: October 27, 2008
Attorney Docket No: **021653-024600US**
For: METHOD AND SYSTEM FOR FORMING CONDUCTIVE BUMPING
WITH COPPER INTERCONNECTION

: **OFFICE OF PETITIONS**


:
: **LETTER**

Dear Inventor Chen:

You are named as a joint inventor in the above-identified United States patent application filed under the provisions of 35 U.S.C. 116 (United States Code) and 37 CFR 1.47(b), Rules of Practice in Patent Cases. Should a patent be granted on the application you will be designated therein as a joint inventor.

As a joint inventor, you are entitled to inspect any paper in the file wrapper of the application, order copies of all or any part thereof (at a prepaid cost per 37 CFR 1.19) or make your position of record in the application. Alternatively, you may arrange to do any of the preceding through a registered patent attorney or agent presenting written authorization from you. If you care to join the application, counsel of record (see below) would presumably assist you. Joining in the application would entail the filing of an appropriate oath or declaration by you pursuant to 37 CFR 1.63.

Telephone inquiries regarding this communication should be directed to Petitions Attorney Kenya A. McLaughlin at (571) 272-3222. Requests for information regarding your application should be directed to the File Information Unit at (703) 308-2733. Information regarding how to pay for and order a copy of the application, or a specific paper in the application, should be directed to Certification Division at (703) 308-9726 or 1-800-972-6382 (outside the Washington D.C. area).


Kenya A. McLaughlin
Petitions Attorney
Office of Petitions

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